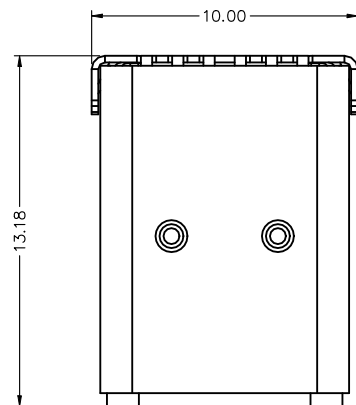
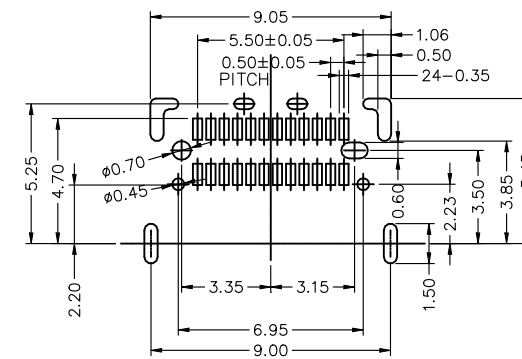
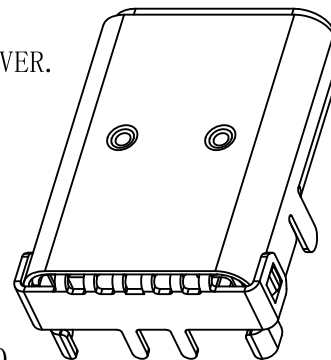


REV	ECN.NO	APPD.
A	XYX-291BZ-24TC-29101	ZHENBO LIU
B	XYX-291BZ-24TC-29101	QiaoZhen LIN



- Note:
1. MATERIAL:SEE TABLE 1
 2. PLATED:
TERMNAL:CONTACT ARER PLTAING Au 30u" .
SOLDER ARER Sn 100u"Min.Ni 50u"Min ALLOVER.
 3. ELECTRIC PERFORMANCE:
INSULATION RESISTANCE: 100MΩ Min.
DIELECTRIC STRENGTH:100 VAC/minute
CONTACT RESISTANCE:40mΩ Max.
 4. PHYSICAL PERFORMANCE:
INSERTION FORCE: 5N~20N .
REMOVE FORCE: 8N~20N .
DURABILITY: 10000 CYCLES.
 5. ALL MATERIAL MUST MEET FOR ROHS 2.0.



P.C.B LAYOUT
GENERAL TOLERANCE ±0.05

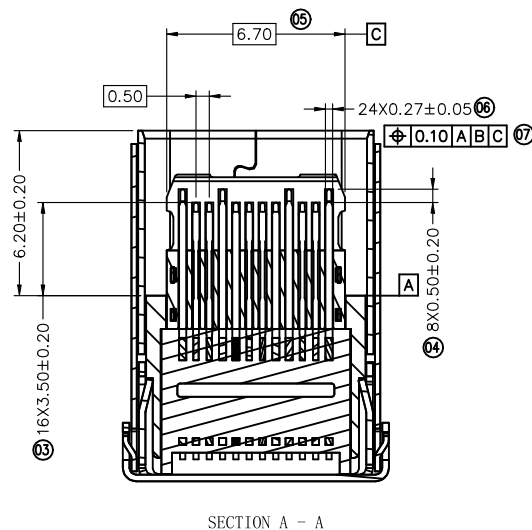
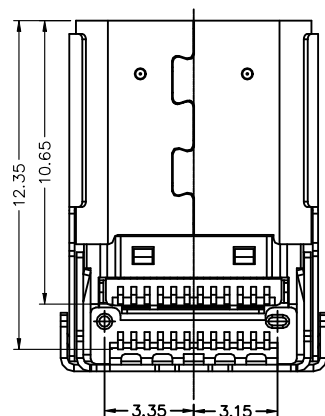
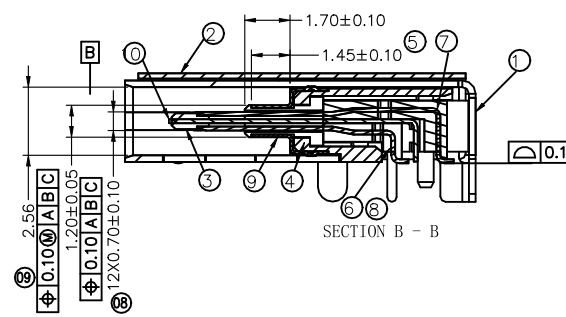
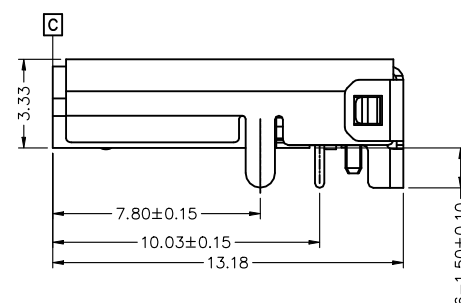
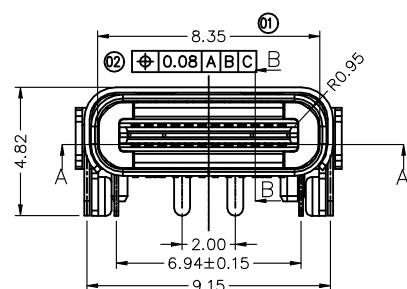


TABLE 1

ITEM	PART NAME	DESCRIPTION	Q' TY
10	MID-PLATE	SUS 镀可焊Ni	1PCS
9	EMC Pad	SUS 镀Ni	2PCS
8	BOTTOM TERMINAL	COPPER ALLOY, CONTACT AREA PLATIND Au30u"	1SET
7	TOP TERMINAL	COPPER ALLOY, CONTACT AREA PLATIND Au30u"	1SET
6	BOTTOM MOLDING	HIGH TEMPERATURE PLASTIC	1PCS
5	TOP MOLDING	HIGH TEMPERATURE PLASTIC	1PCS
4	BACK HOUSING	HIGH TEMPERATURE PLASTIC	1PCS
3	HOUSING MOLDING	HIGH TEMPERATURE PLASTIC	1PCS
2	FRONT SHELL	SUS 镀可焊Ni	1PCS
1	SHELL	SUS 镀可焊Ni	1PCS

TOLERANCES UNLESS NOTED: X ±0.30 ,XX ±0.20 ,XXX ±0.05 ANGLE: X .X±1° THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF RIBAO IN TEECONNECT TECHNOLOGY LIMITED.AND SHALL NOT BE REPRODUCED COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XINYEXING INTERCONNECTEC HNOLGY LIMITEDCT	UNIIS	mm	NAME(INTENDED USE) TYPE C 24P母座 板上双贴SMT 长度L=13.18
	MAT'L		PART NO.(INTENDED USE) XYX-291BZ-24TC-21901
	FINISH		APPD: ZHENBO LIU 12/04'16
	Q'TY		CHKD: QiaoZhen LIN 12/04'16 DR: ZHIYI LI 12/04'16

深圳市日宝电子科技有限公司
Shenzhen RB Electronic Technology Co., Ltd.

CLASS: CONFIDENTIAL SECRET GENERAL

TITLE.: CUSTOMER DRAWING

DWG NO.:

	SHEET	SCALE	REV
	1 / 1	1:1	B